Kingbright

3.2mmx3.6mm FULL-COLOR SURFACE MOUNT LED LAMP

Part Number: APF3236SEEZGQBDC

Hyper Red
Green
Blue

ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

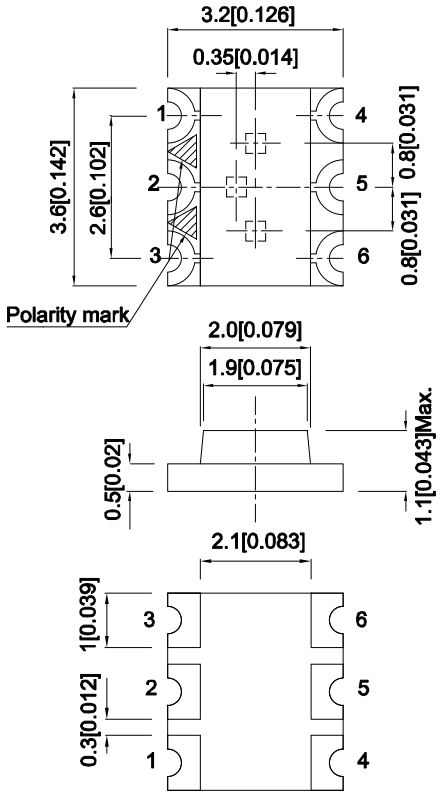
Features

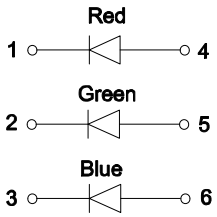
- 3.2mmx3.6mm SMD LED, 1.1mm thickness.
- Low power consumption.
- One red, one green and one blue chips in one package.
- Package : 1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

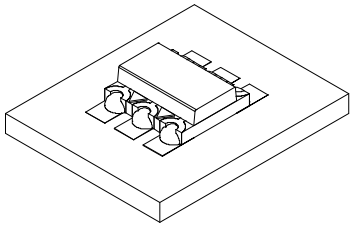
Descriptions

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- The Blue source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions







Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.2(0.008") unless otherwise noted.
3.The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4.The device has a single mounting surface. The device must be mounted according to the specifications.

Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APF3236SEEZGQBDC	Hyper Red (AlGaInP)	Water Clear	80	140	150°
	Green (InGaN)		200	330	
	Blue (InGaN)		40	70	

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous Flux: +/-15%.
3. Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

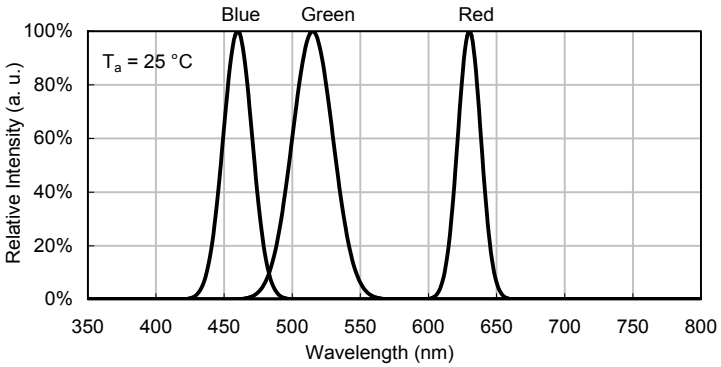
Symbol	Parameter	Emitting Color	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green Blue	630 515 460		nm	I_F=20mA
λD [1]	Dominant Wavelength	Hyper Red Green Blue	621 525 465		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green Blue	20 35 25		nm	I_F=20mA
C	Capacitance	Hyper Red Green Blue	25 45 100		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Hyper Red Green Blue	2 3.3 3.3	2.5 4.1 4	V	I_F=20mA
I_R	Reverse Current	Hyper Red Green Blue		10 50 50	uA	V_R=5V

Notes:
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

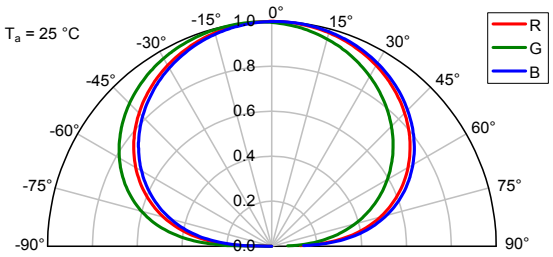
Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Blue	Units
Power dissipation	75	102.5	120	mW
DC Forward Current	30	25	30	mA
Peak Forward Current [1]	195	150	150	mA
Electrostatic Discharge Threshold (HBM)	3000	450	250	V
Reverse Voltage	5			V
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

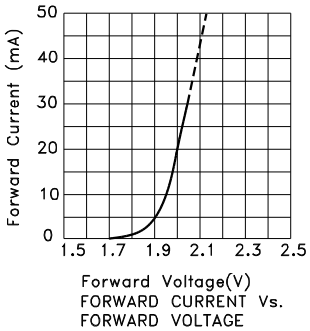
Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

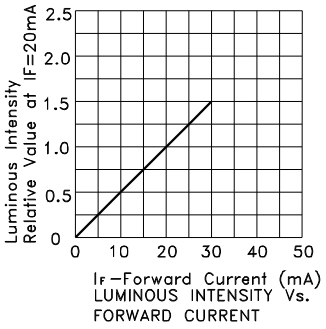


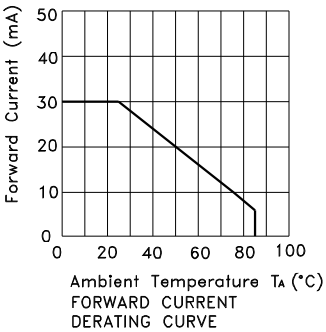
RGB Spatial Distribution

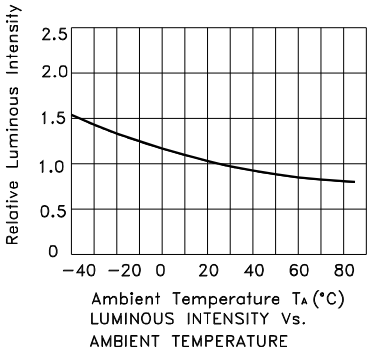


APF3236SEEZGQBDC
Hyper Red

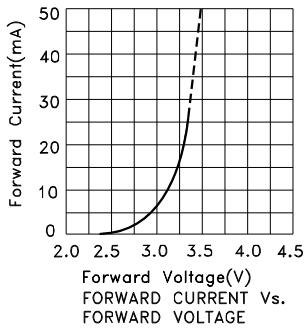




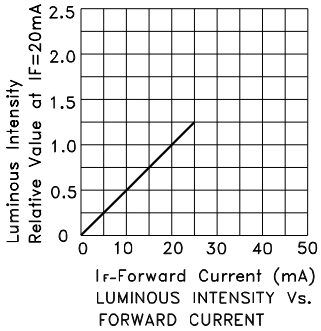




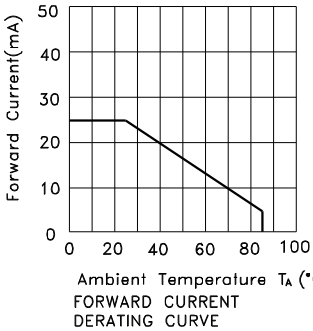
Green



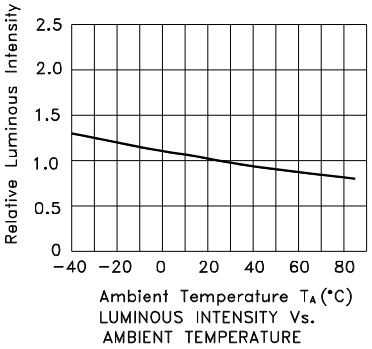
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

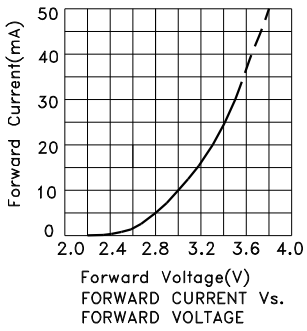


FORWARD CURRENT
DERATING CURVE

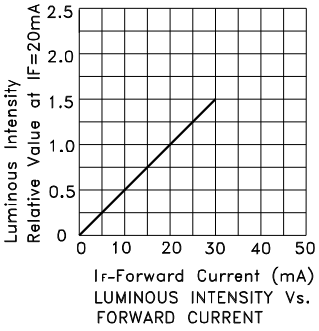


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

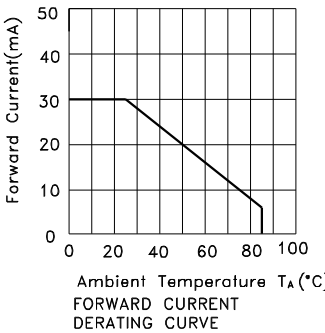
Blue



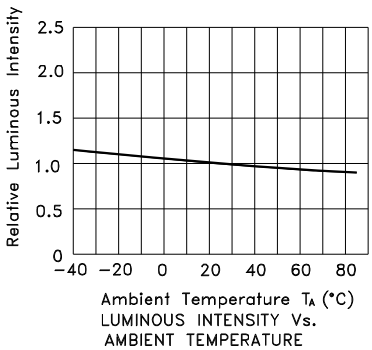
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE

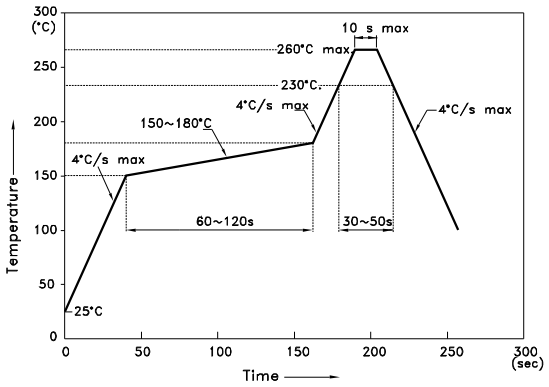


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

APF3236SEEZGQBDC

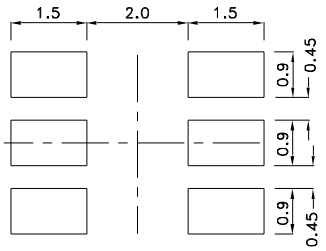
Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

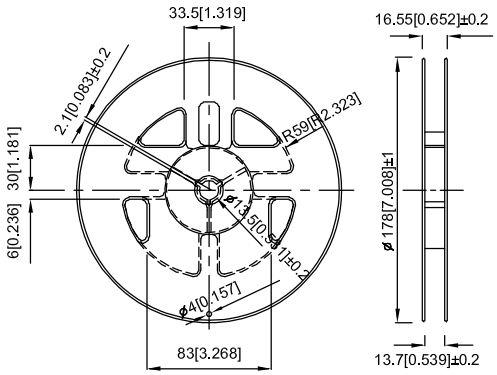


NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

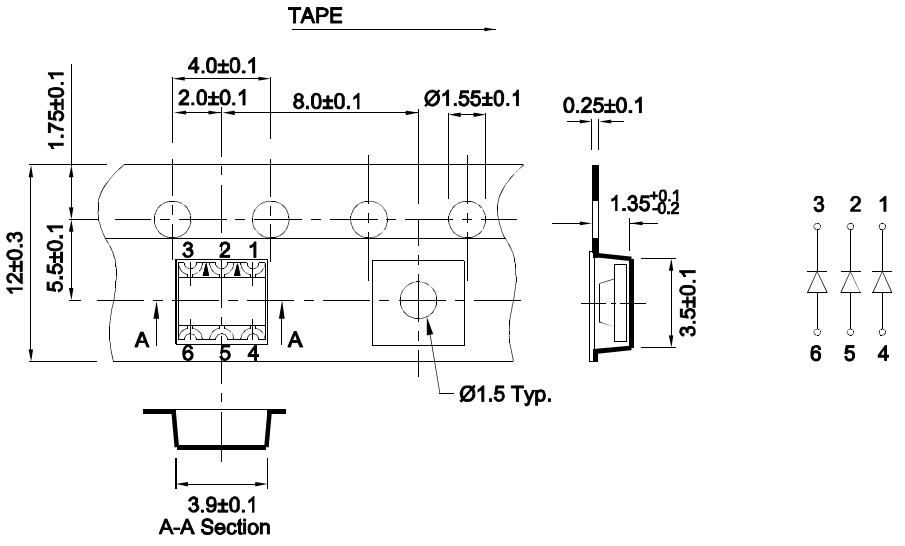
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Dimensions (Units : mm)



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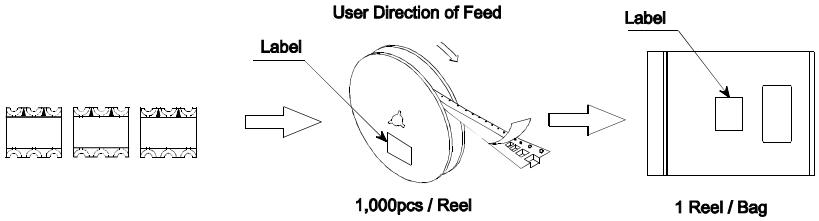
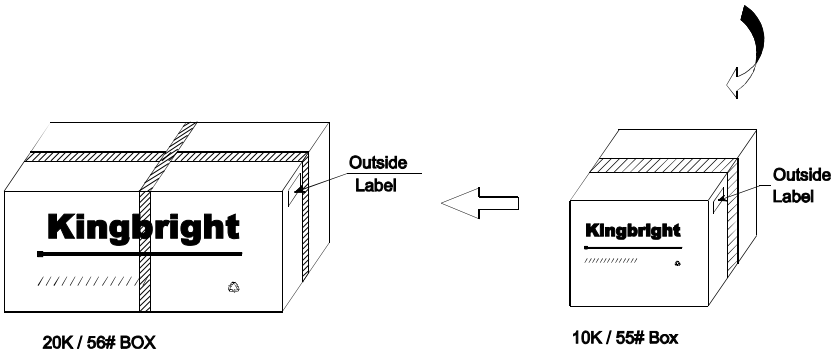
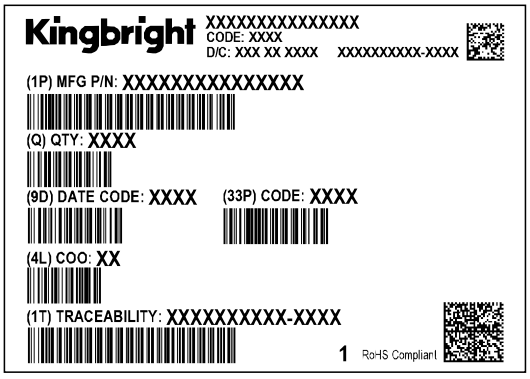
PACKING & LABEL SPECIFICATIONS **APF3236SEEZGQBDC**







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